

AP15P06S Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP15P06S	SOP-8L	AP15P06S XXX YYYY	3000

AP15P06S Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-60	V
VGS	Gate-Source Voltage	±20	V
I₀@Tc=25°C	Continuous Drain Current, -V _{GS} @ -10V ¹	-15	A
I₀@Tc=100℃	Continuous Drain Current, -V _{GS} @ -10V ¹	-8.5	A
IDM	Pulsed Drain Current ²	-45	А
EAS	Single Pulse Avalanche Energy ³	113	mJ
P₀@Tc=25℃	Total Power Dissipation ⁴	52.1	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R₀JA	Thermal Resistance Junction-Ambient ¹	85	°C/W
R₀JC	Thermal Resistance Junction-Case ¹	Thermal Resistance Junction-Case ¹ 2.4	



AP15P06S Electrical Characteristics (Tc=25 $^{\circ}$ Cunless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60	-68		V
$\triangle BVDSS/ \triangle TJ$	BV _{DSS} Temperature Coefficient	Reference to 25 $^\circ\!\!\!{\rm C}$, I_D=-1mA		-0.035		V/℃
	Statia Drain Source On Registeres ²	V _{GS} =-10V , I _D =-12A	20 28			
RDS(ON)	S(ON) Static Drain-Source On-Resistance ² V _{GS} =-4.5V , I _D =-8A			26	33	mΩ
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.6	-2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID2300A		4.28		mV/°C
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}\text{=-}48\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, T_J=25 $^\circ\!\!\mathbb{C}$			1	– uA
1033	Drain-Source Leakage Current	$V_{\text{DS}}\text{=-}48V$, $V_{\text{GS}}\text{=}0V$, $T_{\text{J}}\text{=}55^\circ\!\!\mathbb{C}$			5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	_		±100	nA
gfs	Forward Transconductance	V _{DS} =-10V , I _D =-18A		23		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		7		Ω
Qg	Total Gate Charge (-4.5V)			25	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-4.5V , I _D =- 12A		6.7		
Q_gd	Gate-Drain Charge			5.5		
Td(on)	Turn-On Delay Time			38		
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V , R _G =3.3Ω,		23.6		
Td(off)	Turn-Off Delay Time	I _D =-1A		100		ns
T _f	Fall Time			6.8		
Ciss	Input Capacitance			3635		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		224		pF
Crss	Reverse Transfer Capacitance			141		
ls	Continuous Source Current ^{1,5}				-35	Α
ISM	Pulsed Source Current ^{2,5}	 V_G=V_D=0V , Force Current 			-70	А
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1	V

Note :

1. The data tested by surface mounted on a 1 inch 2 $\,$ FR-4 board with 2OZ copper.

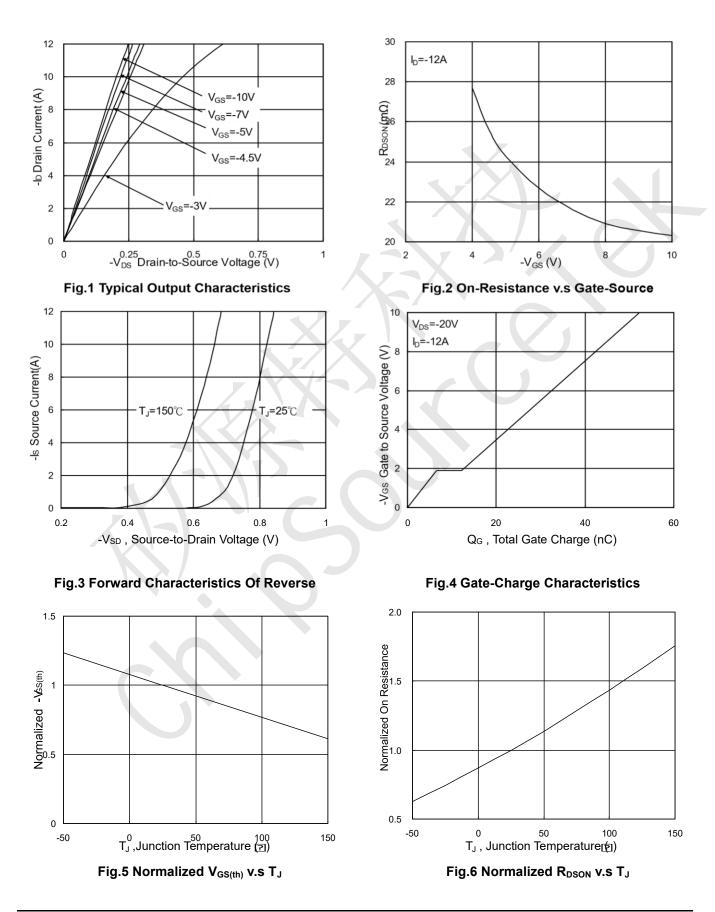
2、 The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$

- 3、The EAS data shows Max. rating . The test condition is VDD=-48V,VGS =-10V,L=0.1mH,IAS =-47.6A
- 4、The power dissipation is limited by 150°C junction temperature

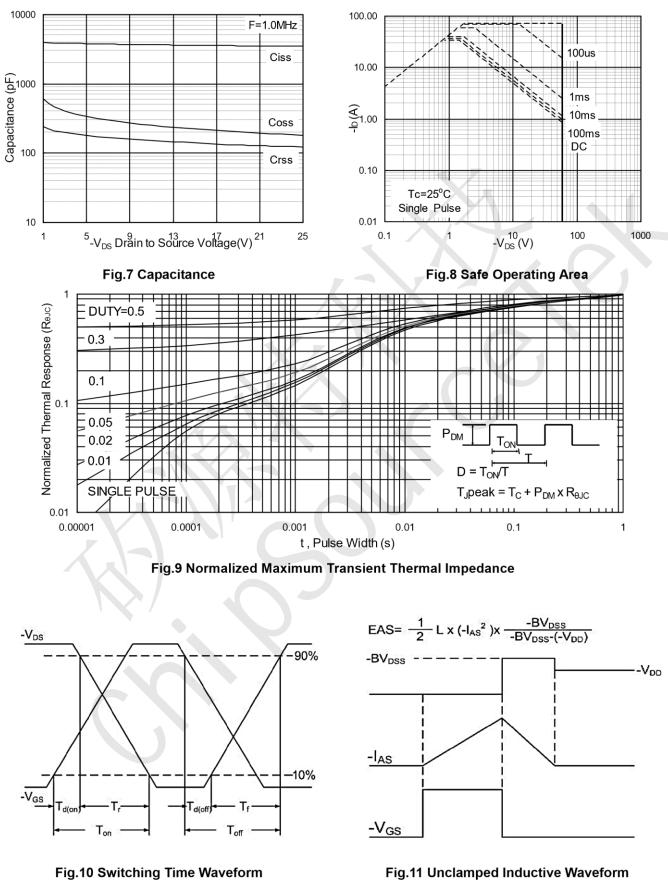
5、The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



AP15P06S Typical Characteristics

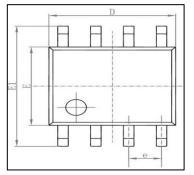


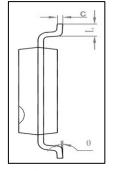


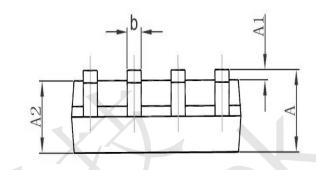




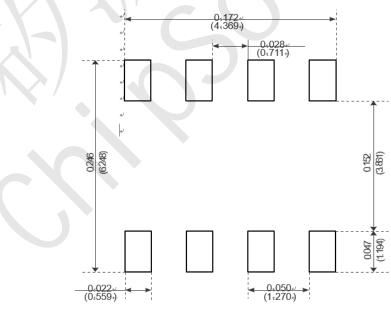
AP15P06S Package Mechanical Data-SOP-8L







Comback	Dimensions Ir	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
A	1.350	1.750	0. 053	0.069
A1	0.100	0. 250	0.004	0.010
A2	1. 350	1. 550	0. 053	0.061
b	0. 330	0. 510	0.013	0. 020
с	0. 170	0. 250	0.006	0.010
D	4. 700	5. 100	0. 185	0. 200
E	3.800	4.000	0.150	0. 157
E1	5.800	6. 200	0. 228	0. 244
е	1.270	(BSC)	0. 050	(BSC)
L	0. 400	1. 270	0.016	0.050
θ	0 °	8°	0°	8°



Recommended Minimum Pads-



深圳市矽源特科技有限公司 ShenZhen ChipSourceTek Technology Co.,Ltd.

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Edition	Date	Change
Rve1.0	2022/1/31	Initial release

